

Conference Programme Day 1, Thursday June 21

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| 08:00-08:30 | Conference Registration and Table Top & Poster Exhibition build up | Table Top & Poster Display Area |
| 08:30-08:45 | Welcome by the EIPC Chairman | Alun Morgan, EIPC, UK |
| Keynote Session 1: Business, Technology & Trends (HMLV) | | Moderator: Alun Morgan, EIPC, UK |
| 08:45-09:15 | Business Outlook: Global Electronics Industry | Walt Custer, Custer Consulting, USA |
| 09:15-09:45 | Advanced substrates and embedded die technology | Emilie Jolivet, Yole Developpement, FR |
| 09:45-10:15 | The Changing Shape of the HDI Market | Roger Massey, Atotech, UK |
| 10:15-10:30 | Panel discussion | |
| 10:30-11:00 | Coffee break | |
| Session 2: European PCB History and Future | | Moderator: Emma Hudson, UL, UK |
| 11:00-11:20 | A Retrospective of 50 Years of the PCB Industry in Europe | Paul Waldner, Multiline International Europa GmbH, DE |
| 11:20-11:50 | The Look ahead Technology drivers for printed circuit boards of tomorrow | Hans Friedrichkeit, PCB-Network, DE |
| 11:50-12:10 | Achieving thermal management improvements with specialised coatings applied on printed circuit board level – possibilities and experiences | Pavel Gentshev, Lackwerke Peters GmbH, DE |
| 12:10-12:20 | Panel discussion | |
| 12:20-13:00 | Networking Lunch | Hotel Restaurant |
| Session 3: Automotive PCB: Safety, Process Reliability and Traceability | | Moderator: Pete Starkey, I-Connect007, UK |
| 13:00-13:20 | Fully integrated factory automation in PCB Technology – the latest PCB 4.0 production approach | Frank Tinnfeld & Michael Luippold, ASS-SAA Luippold Automation System Service, DE |
| 13:20-13:40 | Automation and traceability | Jochen Zeller, AWP Group, DE |
| 13:40-14:00 | Safety in battery cells connecting technology for EV cars | Giacomo Angeloni, Mektec Europe Production GmbH, DE |
| 14:00-14:20 | Functional Safety Requirements for future Automotive electronics | Emma Hudson, UL, UK |
| 14:20-14:30 | Panel discussion | |
| 14:30-14:45 | Coffee Break | |
| Session 4: New PCB Material / Processes for Advanced Application | | Moderator: Martyn Gaudion, Polar Instruments, UK |
| 14:45-15:05 | Why going to Halogen free laminates | Shannon Juan, Elite Material Corporation EMC, TW |
| 15:05-15:25 | Optimizing Laminate and Process Technology to Minimize the RF Impact at High Frequencies (55 to 95GHz) | Alexander Ippich, Isola, DE |
| 15:25-15:45 | The role of design in the IoT exemplar of the Connected Home. User Experiences happen whether you have designed them or not | Russell Morgan, Verisure, SE |
| 15:45-16:00 | Panel discussion | |
| 16:00-19:00 | Departure & visit New Multilayer Factory Unimicron | |
| 19:30 | Celebration & Network Dinner Schloss Walbeck | |
| 23:00 | Return and arrival at Headquarter Hotel Courtyard Hotel Am Seestern | |

The EIPC is not responsible for the content and the presentation of the technical papers, which rests with the presenters. Changes in the programme may occur, due to circumstances, for which the EIPC may not be held responsible.



Conference Programme Day 2, Friday June 22

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| Session 5: Future PCB Design, Material / Processes for the PCB supply chain | | Moderator: Paul Waldner, Multiline International Europa, DE |
| 09:00-09:20 | Digital Solutions for Integrated Automotive PCB Production | Micha Perlman, Orbotech, BE |
| 09:20-09:40 | You already recognize the winner at the start- a supply chain without wastage | Gerd Appelt, Göttle GmbH & Co. KG, DE |
| 09:40-10:00 | Flex for 5G | Jonathan Weldon, DuPont Electronic Materials, USA |
| 10:00-10:20 | Printed Electronics: a method to create curved, flexible and stretchable printed circuit boards | Jaap Lombaers + Corne Rentrop, TNO, NL |
| 10:20-10:50 | 30 minutes Coffee break | Table Top & Poster Display Area |
| 10:50-11:10 | The New Proportional Land Dimensioning Concept | Rainer Taube, Fachverband für Design, Leiterplatten- & Elektronikfertigung (FED), DE |
| 11:10-11:30 | Recent developments in Lab-on-PCB technology | Dr. Despina Moschou, University of Bath, UK |
| 11:30-11:50 | Circuit Data, an Open Source Language for communicating PCB Specification | Jan Perderson, Elmatica, NO |
| 11:50-12:00 | Panel discussion | |
| 12:00-13:00 | Networking Lunch | Hotel Restaurant |
| Session 6: New Material / Processes for PCB Manufacturing | | Moderator: Oldrich Simek, Pragoboard, CZ |
| 13:00-13:20 | A study of the initiation speed of the palladium, within an electroless nickel, electroless palladium and immersion gold (ENEPIG) system, with regard to solder joint reliability | Rick Nichols, Atotech, DE |
| 13:20-13:40 | A Review of Metallization Interfaces on Microvia Reliability | Richard Bellemare, MacDermid Enthone Electronics Solutions, DE |
| 13:40-14:00 | Traceability and Paramaterized Optical Inspection | Andre Bodegom, Adeon, NL |
| 14:00-14:20 | Be Flexible. Go Digital. Inkjet: more than the traditional way to apply solder resist | Rita Torfs, Agfa Materials, BE |
| 14:20-14:40 | New technologies for solder mask application | Peter Strohm, Notion System GmbH, DE |
| 14:40-15:00 | Panel discussion | |
| 15:00-15:10 | Chairman closing remarks - End of conference day 2 | |

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